



The DNA of tech.™

eSMP® (enhanced Surface-Mount Power) Series Package Technology

Small, Low Profile Package Solutions for Rectifiers Product Technologies



BENEFITS

- ✓ enhanced Surface-Mount Power (eSMP®) packages are small, low profile solutions for select rectifier product technologies
- ✓ Better thermal performance and reliability
- ✓ Space-saving miniature packages allow for low profile, high density end products
- ✓ Available in asymmetrical and symmetrical flat-type packages
- ✓ Higher current and power efficiency



AUTOMOTIVE APPLICATIONS

- Engine Vehicle Control Units
- Powertrain Injection Control and Fuel Pumps
- Chassis Controls
- Body Electronics
- Active Safety
- Passive Safety
- Exterior Lighting
- HEV and FEV
- Engine Cooling
- Exhaust Control Systems

PACKAGE SOLUTIONS

MicroSMF (DO-219AC)	MicroSMP (DO-219AD)	SMF (DO-219AB)	SMP (DO-220AA)	SlimSMAW (DO-221AD)	SlimSMA (DO-221AC)	SMPA (DO-221BC)	SMPC (TO-277A)	SlimDPAK (TO-252AE)	SMPD (TO-263AC)

TECHNOLOGIES

TMBS® RECTIFIERS

- Trench MOS Schottky technology
- Reverse voltage from 45 V to 200 V
- Current range from 1 A to 60 A
- Enable higher current and power efficiency with a unique design that promotes better thermal performance and reliability

FRED Pt® RECTIFIERS

- FRED Pt® (Fast Recovery Epitaxial Diodes) products are based on a Pt doping technology
- Current range from 1 A to 30 A
- Reverse voltage: 100 V, 200 V, and 600 V
- Fast and soft recovery characteristics

STANDARD RECTIFIERS

- Electrical static discharge (ESD) capability
- Oxide planar chip technology
- Current range from 0.7 A to 20 A
- Reverse voltage from 100 V to 600 V

RESOURCES

